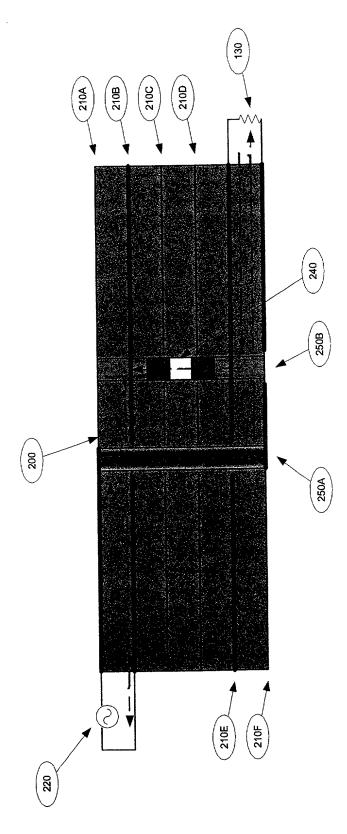


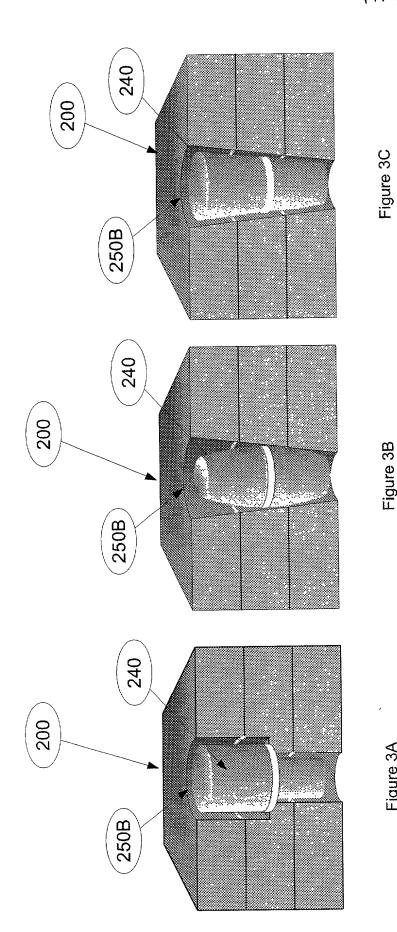
Figure 1 (Prior Art)



-igure

Figure 3B

Figure 3A



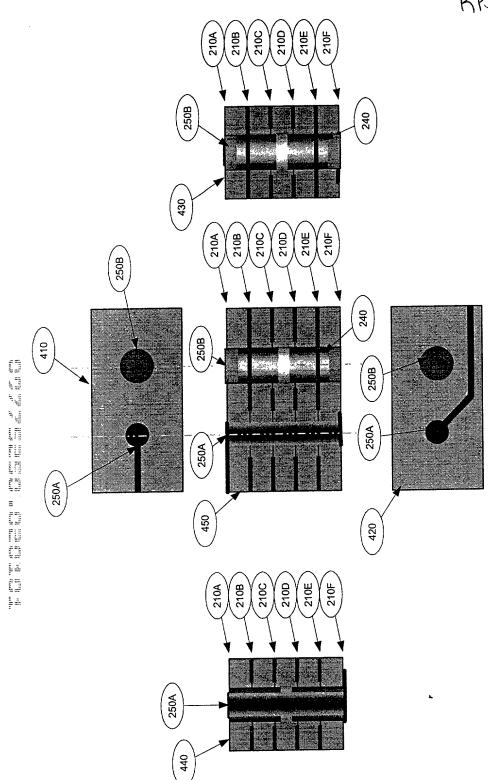


Figure 4

500

Figure 5

Forming a printed circuit board comprising a plurality of conductive layers and two or more vias interconnecting two or more conductive layers of the plurality of conductive layers

Embedding an electrical component in the via that forms part of the reference path between two separate inner conductive layers of the plurality of conductive layers within the printed

circuit board

520

570

600

Figure 6

Forming a printed circuit board comprising a plurality of conductive layers and two or more vias interconnecting two or more conductive layers of the plurality of conductive layers

Embedding an electrical component in any particular via between any two separate conductive layers of the plurality of conductive layers within the printed circuit board

620

610